



TRANSLATION FROM JAPANESE OF  
A PORTION OF OFFICE ACTION DATED DECEMBER 24, 2002  
IN JAPANESE PATENT APPLICATION 11-102965

This application is to be rejected for the reasons given below. Any response should be submitted within 60 days of this mailing.

REASON

The invention according to the claims given below is an invention which could have been made easily on the basis of the invention described in the following publications published within Japan prior to its filing and hence cannot be patented pursuant to Japanese Patent Law 29-2.

STATEMENT

Claims: 1 - 4

Cited Reference: 1

REMARKS:

Reference 1 substantially discloses "a temperature sensor characterized as comprising wherein "a lead line (lead line 106 of teflon-coated nickel wires or its combination with a stainless steel support plate 104A) ) is attached to a terminal electrode formed on a temperature detecting element (thermistor element 101A) and said lead line is elastic."

Reference 1 also discloses that "the lead line 106 of teflon-coated nickel wires is insulatingly covered" (claim 3 of the present application. (Note "covered by spherical glass 110" and "lead lines ... coated with teflon").

To use "phosphor bronze, german silver, beryllium, SUS, Cu-Ti alloys with or without plating" in order "to make elastic" (claim 2 of the present application) may be believed well known as disclosed in Reference 1 ("stainless steel supporting plate 104A" as a material for providing "elasticity").

RECEIVED  
JAN 24 2003  
IC 2800 MAIL ROOM

It is believed well known to form a "temperature detecting element" with a "negative temperature coefficient thermistor element." (invention of claim 4 of the present application).

List of Cited References:

- 1: Patent Publication Tokkai 61-5269